

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S2	3068	diffusion and S1	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/25 13:35
S1	27267	solder near bump	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/25 13:35
S5	44	S2 and S3 and S4	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/25 13:36
S4	15823	diffusion near coefficient	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/25 13:36
S3	361505	(melting near point) (melting-point) (melting\$1point)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/25 13:36
L6	1	"10577450".rlan. or ("10".src. and "577450".ap.)	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2008/09/25 14:44
L8	55416	(gold Au) with (bump ball contact)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/25 14:49
L7	9033	gold near2 (bump ball)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/25 14:49
L12	858	diffusion and 11	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/25 14:52

L11	1843	8 and 9 and 10	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/25 14:52
L10	539137	Sn Tin	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/25 14:52
L9	34349	TiW (titanium near tungsten) titanium/ tungsten Ti/W	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/25 14:52
L14	280	12 and 13	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/25 14:53
L13	365737	melt\$ near point	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/25 14:53
L15	20329	(gold Au) with (bump ball)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/25 14:54
L16	204	15 and 9 and 10 and diffusion and (melt\$3 near (point temperature))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/25 14:55
L18	43	((Au gold) near bump) and 16	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/25 15:04
L21	92	19 and 20	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/25 15:10
L20	6553	(gold Au) and (Sn tin) and 9	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/25 15:10

L19	804	(257/781).CCLS.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/09/25 15:10
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**9/25/2008 3:39:52 PM**

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Bump Electrode.wsp**